CALL FOR PAPERS – ISPD 2020
ACM International Symposium on Physical Design
with a tribute to Dr. Louis K. Scheffer

http://www.ispd.cc
March 29 – April 1, 2020
Taipei, Taiwan
Sponsored by ACM SIGDA with Technical Co-sponsorship from IEEE CAS

The International Symposium on Physical Design provides a premier forum to exchange ideas and promote research on critical areas related to the physical design of VLSI systems. All aspects of physical design, including its interactions with architecture, behavioral and logic-level synthesis, and back-end performance analysis and verification are within the scope of the symposium. Target domains include semi-custom and full-custom ICs, ASICs, FPGAs, and systems-on-chip/systems-in-package. In 2020, the 29th symposium will highlight key new directions and leading-edge theoretical and experimental contributions to the field. The ACM Press will publish accepted papers in the symposium proceedings. ISPD will recognize excellent contributions through a Best Paper Award. Topics of interest include but are not limited to:

Floorplanning and interconnect planning
Partitioning, placement, and routing
Physical design for manufacturability and yield
Synthesis optimizations within physical design
Estimation and modeling
Timing and crosstalk issues in physical design
Special structures for clocking and power networks
Physical design for emerging process technologies

Interactions with system and logic level design
Analysis and management of power dissipation
Management of design data and constraints
New physical design methodologies
Physical design for FPGAs
Circuit analysis in a physical design context
Multi-threaded/distributed physical design algorithms
Hardware security related physical design

IMPORTANT DATES

<table>
<thead>
<tr>
<th>Event</th>
<th>Deadline</th>
</tr>
</thead>
<tbody>
<tr>
<td>Title and abstract submission</td>
<td>September 30, 2019</td>
</tr>
<tr>
<td>Full manuscript submission</td>
<td>October 7, 2019</td>
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<tr>
<td>Acceptance notification</td>
<td>November 11, 2019</td>
</tr>
<tr>
<td>Camera-ready paper due</td>
<td>January 31, 2020</td>
</tr>
</tbody>
</table>

SUBMISSION OF PAPERS

All papers must be submitted electronically at https://easychair.org/conferences/?conf=ispd2020. Details will be posted on http://www.ispd.cc. Potential authors must submit full-length, original, unpublished papers (a maximum of 8 pages in ACM conference format) with an abstract up to 200 words and contact author information (name, mailing address, telephone/fax, e-mail). Papers previously published or currently submitted for publication to other conferences/journals will not be considered. If related papers have been previously published or are currently submitted elsewhere for publication, the authors must clearly state the differences between these and the current submission. Submitted papers will be under blind review, so must not include names or affiliations of the authors anywhere in the manuscripts. Failure to comply with these requirements will result in automatic rejection.

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